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APPLICATION NO. 09/785,436

DATE 02/20/2001

FIRST NAMED INVENTOR

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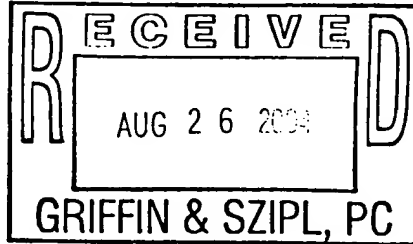
TM&K0007

CONFIRMATION NO.

8173

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08/24/2004



EXAMINER

GEYER, SCOTT B

ART UNIT

PAPER NUMBER

2829

DATE MAILED: 08/24/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

"Exhibit A"



UNITED STATES PATENT AND TRADEMARK OFFICE

UNDER SECRETARY OF COMMERCE FOR INTELLECTUAL PROPERTY AND
DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE

NOTICE OF DRAWING INCONSISTENCY WITH SPECIFICATION

The drawings filed 11-4-03 have been received. However, an inconsistency exists between the drawings and the Brief Description of the Drawings in the specification.

Figures are listed in the Brief Description of the Drawings in the specification but not contained in the Drawings.

Figures 2, 3 are contained in the Drawings but not listed in the Brief Description of the Drawings in the specification.

Applicant is required to correct the above-noted inconsistency within a time period of **ONE MONTH or THIRTY (30) DAYS, whichever is longer**, from the mailing date of this Notice, or within the time remaining in the time period set forth in the Notice of Allowability (Form PTOL-37) to file corrected drawings, whichever is longer. **NO EXTENSION OF THIS TIME PERIOD MAY BE GRANTED UNDER EITHER 37 CFR 1.136 (a) OR (b)**

Failure to correct the above noted inconsistency will result in **abandonment** of the application.

The file will be held in the Publishing Division to await the correction of the inconsistency.

Return Corrected Drawings/Specification to:

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FORM PTO-1631 (REV. 10-03)

"Exhibit B"



carrying out die-bonding under conditions of a temperature of from 150°C to 250 °C, a bonding time of 0.1 (inclusive) second to 2 seconds and a pressure of 0.1 gf/mm² to 4 gf/mm².

BRIEF DESCRIPTION OF THE DRAWINGS

5 Fig. 1 cross-sectionally illustrates an example of a process for fabricating the semiconductor device of the present invention.

Fig. 2 is a front elevation used to describe a method for measuring peel strength by using a push-pull gauge.

Fig. 3 is a plan view of an example of lead frames having a die pads.

10 BEST MODE FOR CARRYING OUT THE INVENTION

The present invention will be described below in greater detail by giving Examples, but an embodiment of the present invention is not limited to these examples. All of polyimides used in the following examples are obtained by heating the mixture of acid dianhydride with diamine being the same mol as
15 the acid dianhydride, in solvent, so as to polymerize them. In the following examples, polyimide A is a polyimide synthesized from 1,2-(ethylene)bis(trimellitate anhydride) and bis(4-amino-3,5-dimethylphenyl)methane; polyimide B is a polyimide synthesized from 1,2-(ethylene)bis(trimellitate anhydride) and 4,4'-diaminodiphenylether; polyimide
20 C is a polyimide synthesized from 1,2-(ethylene)bis(trimellitate anhydride) and bis(4-amino-3,5-diisopropylphenyl)methane; polyimide D is a polyimide synthesized from 1,2-(ethylene)bis(trimellitate anhydride) and 2,2-bis[4-(4-